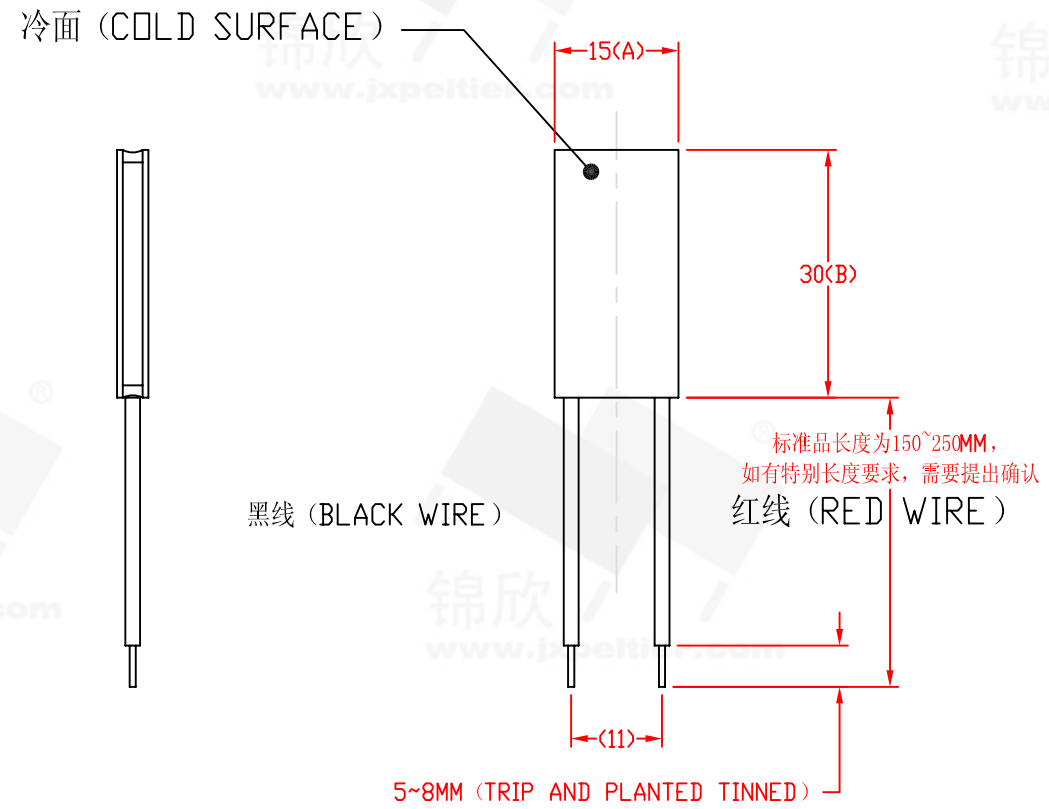


REVISIONS						
REV.	POS.	DESCRIPTION	DATE	DRW	APP	ECN#
A		INITIAL CREATION	2008/03/12	GARY	JUNSON	



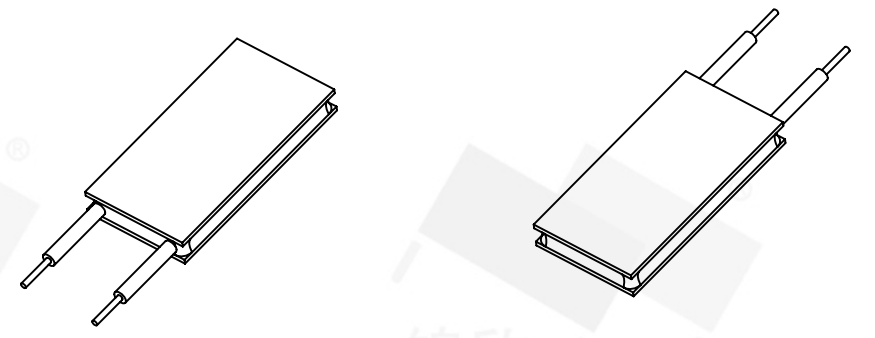
TEC 1 - 063 XX 15 30

热致冷组件 陶瓷结构式 级数 电堆数 最大电流 外形尺寸(A) 外形尺寸(B)

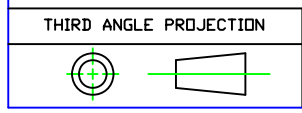
注意事项:

1. 半导体致冷片总成厚度公差为 ± 0.2 , 客户在和散热片组装时, 需要考量此公差带, 不得压得太紧, 也不能压得太松, 否则会导致半导体致冷片破裂或降低功效。
2. 半导体致冷片在通电前, 检查是否有安装符合要求当量的散热片, 禁止空载, 否则会因工作所产生热源没有传递走而烧坏。
3. 标准的半导体致冷片型号及规格参数如下列表 (如有更改, 不另行通知, 非标规格需要定制, 请联络销售部):

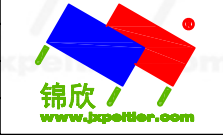
序号 ITEM	型号 PART NUMBER	电堆数 COUPLES	最大电流 A (MAX)	最大电压 V (MAX)	最大冷量(W) 室温环境TH=27°	最大温差(°C)	外形尺寸(MM)			电阻 Ω	重量 g
							A	B	H 实物为准		
1	TEC1-063021530	063	2	7.5	9.4	66	15	30	4.4	--	--
2	TEC1-063031530		3		14	66	15	30	3.5	--	--
3	TEC1-063041530		4		18.7	66	15	30	3.1	--	--
4	TEC1-063051530		5		23.4	66	15	30	2.9	--	--



*DO NOT SCALE DRAWING



THIS DRAWING AND THE DATA DISCLOSED HEREIN OR HEREWITH IS NOT TO BE REPRODUCED USED OR DISCLOSED OR IN PART TO ANYONE WITHOUT THE PERMISSION OF JXPELTIER (SUZHOU) CO., LTD.

1. UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE MM 2. TOLERANCE ARE AS FOLLOWS: 0 < X < 2 ± 0.06 2 < X < 10 ± 0.08 10 < X < 50 ± 0.12 50 < X < 100 ± 0.16 100 < X < 200 ± 0.20 200 < X < 300 ± 0.30 ANGLES ± 0.5°	Part NO.	TEC1-063xx1530	DESCRIPTION	DC 7.5V(Max), 3~5A, 063晶堆, 单层, 冷端15x30, 热端15x30mm		
	SIGNATURE		DATE		 锦欣制冷 (苏州) 有限公司 JXPELTIER (SUZHOU) CO., LTD Tel/Fax: +86-512-62539286 Mobile: +86-18061938176 emailto: jxpeltier@gmail.com http://www.jxpeltier.com	
	DRAWN BY	GARY	2008/03/12			
	CHECKED BY	JACK	2008/03/12			
	ENGR	VIVI	2008/03/12			
APPROVED BY	JASON	2008/03/12	CAD MDDLE:	SCALE: 1:1	REV: A	
MATERIAL:	ISSUED BY	LILY	2008/03/12	CAD DWG:	SIZE: A3	SHEET: 1 OF 1